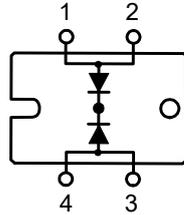
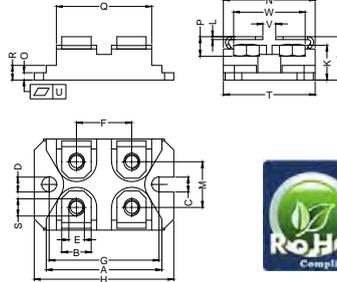


MBR2X160-100NB thru MBR2X160-200NB

High T_{jm} Low IRRM Schottky Barrier Diodes



Dimensions SOT -227(ISOTOP)



Dim.	Millimeter		Dim.	Millimeter	
	Min.	Max.		Min.	Max.
A	31.30	31.65	M	12.00	13.00
B	7.80	8.40	N	25.15	25.65
C	4.00	4.30	O	1.95	2.15
D	∅4.00	∅4.30	P	5.60	6.60
E	4.00	4.30	Q	25.30	26.30
F	14.90	15.20	R	3.90	4.30
G	30.10	30.30	S	4.45	4.85
H	38.00	38.50	T	24.50	25.10
J	12.10	12.90	U	0.05	0.10
K	9.00	9.60	V	3.00	4.80
L	0.75	0.85	W	19.30	20.50

	V _{RSM} V	V _{RRM} V
MBR2x160-100NB	100	100
MBR2x160-150NB	150	150
MBR2x160-200NB	200	200

Symbol	Test Conditions	Maximum Ratings	Unit
IFRMS	T _C =95°C; rectangular, d=0.5; Per Chip	200	A
IFAVM	T _C =95°C; rectangular, d=0.5; Per Chip	160	
IFAVM	T _C =95°C; rectangular, d=0.5; per device	320	
IFSM	T _{VJ} =45°C; t _p =10ms (50Hz), sine	1400	A
EAS	I _{AS} =17A; L=180uH; T _{VJ} =25°C; non repetitive	31	mJ
IAR	V _A =1.5·V _{RRM} typ.; f=10kHz; repetitive	1.7	A
(dv/dt)_{cr}		5000	V/us
T_{VJ}		-40...+150	°C
T_{VJM}		150	
T_{stg}		-40...+150	
P_{tot}	T _C =25°C	410	W
M_d	mounting torque (M4); terminal connection torque (M4)	1.1-1.5/9-13	Nm/lb.in.
Weight	typical	30	g

Symbol	Test Conditions	Characteristic Values			Unit
		typ.	max.		
I_R	T _{VJ} =25°C; V _R =V _{RRM} T _{VJ} =125°C; V _R =V _{RRM}		4 40		mA
V_F	I _F =160A; T _{VJ} =125°C I _F =160A; T _{VJ} =25°C I _F =320A; T _{VJ} =125°C	100V 0.75 0.88 0.95	150V 0.77 0.91 0.99	200V 0.85 0.95 1.10	
R_{thJC} R_{thCH}		0.15		0.30	K/W

FEATURES

- * International standard package SOT-227
- * Very low V_F
- * Extremely low switching losses
- * Low I_{RM}-values
- * RoHS compliant

APPLICATIONS

- * Rectifiers in switch mode power supplies (SMPS)
- * Free wheeling diode in low voltage converters

ADVANTAGES

- * High reliability circuit operation
- * Low voltage peaks for reduced protection circuits
- * Low noise switching
- * Low losses

Sirectifier®

MBR2X160-100NB thru MBR2X160-200NB

High T_{jm} Low IRRM Schottky Barrier Diodes

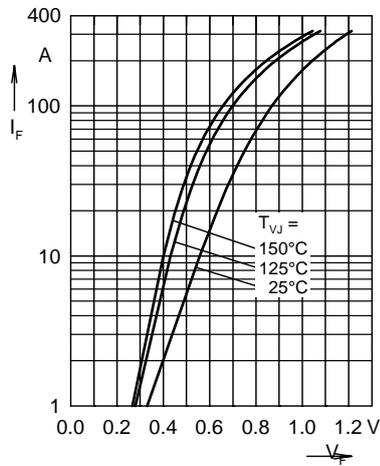


Fig. 1 Max. forward voltage drop characteristics

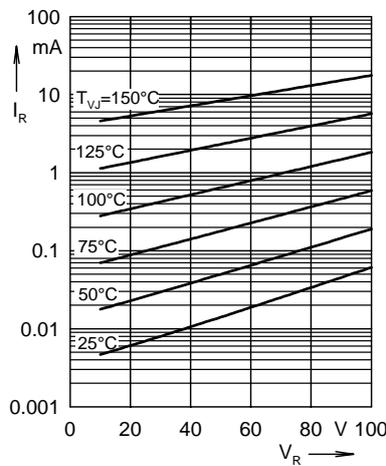


Fig. 2 Typ. reverse current I_R vs. reverse voltage V_R

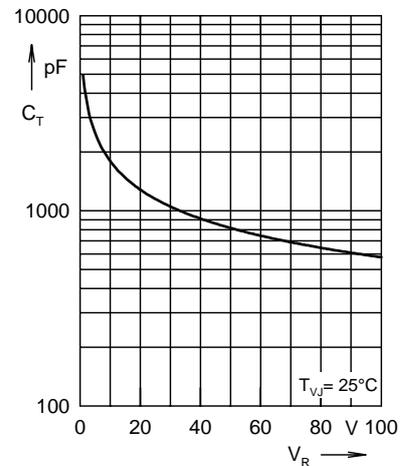


Fig. 3 Typ. junction capacitance C_T versus reverse voltage V_R

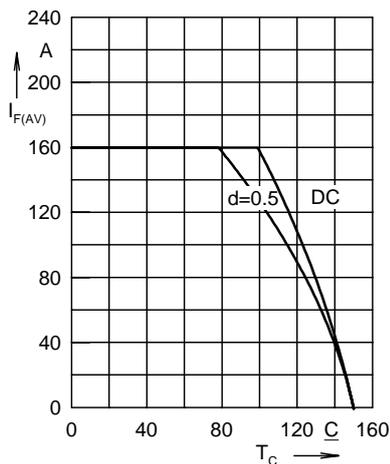


Fig. 4 Avg. forward current $I_{F(AV)}$ vs. case temperature T_C

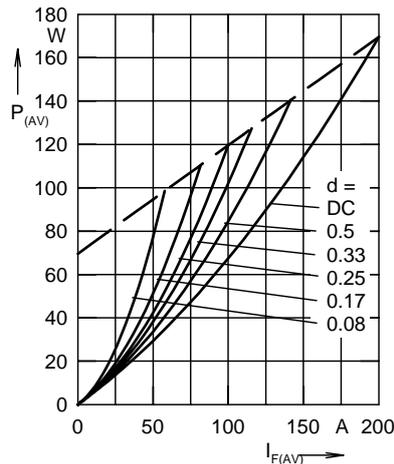


Fig. 5 Forward power loss characteristics

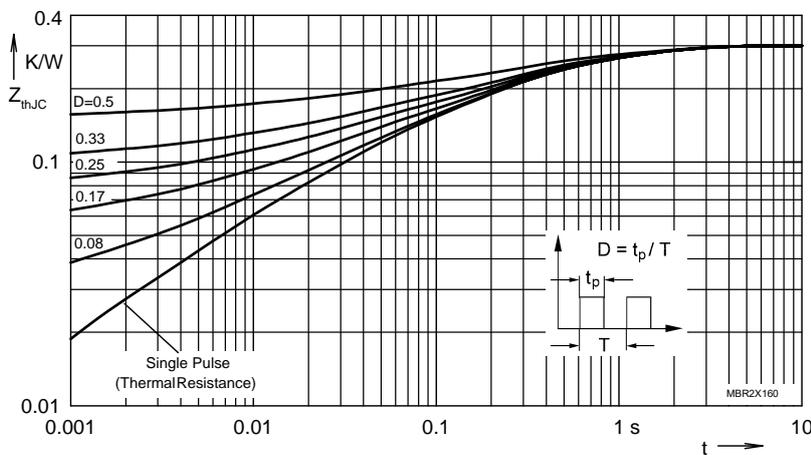


Fig. 6 Transient thermal impedance junction to case at various duty cycles

Note: All curves are per diode

